

Claims

1. A method of fabricating a printed circuit board assembly, comprising:
 - molding an array including a plurality of circuits that are physically interconnected, each integrated circuit having a molded body defining a lower surface, each integrated circuit having a plurality of electrical contacts on the bottom surface;
 - singulating the array to form a plurality of separate integrated circuits and cut at least a portion of the electrical contacts;
 - applying an organic solderability preservative to the cut portions of the electrical contacts;
 - applying heat to dry the integrated circuits;
 - soldering the integrated circuits to a printed circuit board by applying molten solder to remove the organic solderability preservative.
2. The method of claim 1, wherein:
 - the array is singulated utilizing a sawing process; and
 - the organic solderability preservative is applied during the sawing process.
3. The method of claim 1, wherein:
 - the organic solderability preservative is applied by dipping after singulation.
4. The method of claim 1, wherein:
 - the organic solderability preservative is applied by spraying after singulation.
5. The method of claim 1, wherein:
 - the array is singulated by shearing the array utilizing a punch and die.

6. The method of claim 1, including:
cleaning the electrical contacts with an etching material prior to application of the organic solderability preservative.

7. The method of claim 1, wherein:
the integrated circuit includes an exposed die paddle on the lower surface.

8. A method of fabricating an integrated circuit package, comprising:
molding an array including a plurality of circuits that are physically interconnected, each integrated circuit having a molded body defining a lower surface, each integrated circuit having a plurality of electrical contacts on the bottom surface;
singulating the array into a plurality of separate integrated circuits by sawing the array;
applying an organic solderability preservative to at least a portion of the electrical contacts;
applying heat to dry the organic solderability preservative.

9. The method of claim 8, wherein:
the organic solderability preservative is applied by dipping after singulation.

10. The method of claim 8, wherein:
the organic solderability preservative is applied by spraying after singulation.

11. The method of claim 8, including:
cleaning the electrical contacts with an etching material prior to application of the organic solderability preservative.

12. The method of claim 8, wherein:
the organic solderability preservative comprises an imidazole compound.

13. A method of fabricating an integrated circuit package,
comprising:

fabricating an array including a plurality of circuits that are
physically interconnected, each integrated circuit having a body defining a
lower surface, each integrated circuit having a plurality of electrical contacts
on the bottom surface;

singulating the array into a plurality of separate integrated
circuits by cutting the array;

applying an oxidation inhibiting agent to at least a portion of the
electrical contacts.

14. The method of claim 13, wherein:
the oxidation inhibiting agent is applied in a liquid form; and
including:

applying heat to dry the organic solderability preservative.

15. The method of claim 14, wherein:
the oxidation inhibiting agent is an organic solderability
preservative.

16. The method of claim 15, wherein:
the organic solderability preservative is applied by dipping after
singulation.

17. The method of claim 15, wherein:
the organic solderability preservative is applied by spraying
after singulation.

18. The method of claim 15, including:
cleaning the electrical contacts with an etching material prior to
application of the organic solderability preservative.

19. The method of claim 15, wherein:
the organic solderability preservative comprises an imidazole
compound.